

U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICELIST OF ART CITED BY APPLICANT
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U.S. PATENT DOCUMENTS

*Examiner Initial		Document Number	Date	Name	Class	Subclasses	Filing Date If Appropriate
	AA	5,612,574	3/18/97	Summerfelt et al.			
	AB	5,719,333	2/17/98	Hosoi et al.			
	AC	5,831,333	11/3/98	Malladi et al.			
	AD	5,919,548	7/6/99	Barron et al.			
	AE	5,551,283	9/3/96	Manaka et al.			
	AF	5,492,011	2/20/96	Amano et al.			
	AG						
	AH						
	AJ						

FOREIGN PATENT DOCUMENTS

		Document Number	Date	Country	Class	Subclasses	Translation	
							Yes	No
	AK							
	AL							
	AM							
	AO							

OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)

EV085429433	AP		"NTC and PTC Thermistors"; http://www.thermodisc.com/ntcptc.html ; 1/7/98; 2 pages.
	AR		"DI-5B35 Linearized 4-Wire RTD Input"; http://www.dataq.com/di5b35.html ; 1/7/98; 2 pages.
	AS		"RTD"; http://www.mtsensors.com/rtds.html ; 1/7/98; 3 pages.
	AT		"Low Cost Thermal-Ribbon (TM) uses thin film RTD"; http://www.minco.com/s17624nr.html ; 1/7/98; 1 page.
	AU		"Silicon Processing for the VLSI Era"; Volume 1 - Process Technology; Second Edition; S. Wolf et al.; 2000; pps 22-25 and pps. 841-845.

EXAMINER

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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.